Product/Process Change Notification

N° 2022-128-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Change of die separation process for SiC diode in product AIKW50N65RF5

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2023-01-17.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46“, which stipulates:
  “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
  Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

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Product/Process Change Notification

N° 2022-128-A

Products affected — Please refer to attached affected product list PCN_2022-128-A_[customer-no].pdf

Detailed change information

Subject: Change of die separation process for SiC diode in product AIKW50N65RF5

Reason/Motivation: Improvement of manufacturing process in order to increase throughput capacity.

Description	Old	New
PROCESS - ASSEMBLY: Die scribe or separation	Wafer separation is carried out by laser dicing	Wafer separation is carried out by mechanical dicing

Product identification

Traceability assured via date code.
No change in SP ordering number.

Anticipated impact of change

No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit and function.

DeQuMa-ID(s): SEM-PA-19

Attachments

PCN_2022-128-A_[customer-no].pdf	affected product list

Time schedule

Final qualification report	available, provided upon request
First samples available	on request
Intended start of delivery [1]	2023-06-07
Last order date (LOD) [2]	2023-06-07
Last delivery date (LDD) [3]	2023-12-07

[1] Provided date or earlier after customer approval.
[2] Last date where orders for unchanged products will be accepted.
[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

If you have any questions, please do not hesitate to contact your local sales office.

PCN 2022-128-A

Change of die separation process for SiC diode in product AIKW50N65RF5

Affected products sold to DIGI-KEY (4002348)

Sales name	SP number	OPN	Package	Customer part number
AIKW50N65RF5	SP001724852	AIKW50N65RF5XKSA1	PG-TO247-3-41	AIKW50N65RF5XKSA1